Macro Semi 3D Metrology

Wafer Metrology: 2D & 3D Inspection

Artificial Intelligence

Tag and train images
to classify and quantify defects.

BrighTex Clarity

First system in the world to do wafer 3D & 2D analysis simultaneously

- Increase your yield with the most advanced A.I. in semiconductor metrology.

- BTBP's system detects and quantifies process defects.

- Wafer metrology is the key to process control and yield enhancement.

BTBP
BTBP's A.I. technology to increase your yield
BrighTex Bio-Photonics

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How it works

- Load & scan the wafer.
- Capture the full wafer for 2D and 3D analysis.
- Recipe setup and binning capability.
- Classify wafer defects and generate highest resolution 3D models for quantitative measurements.
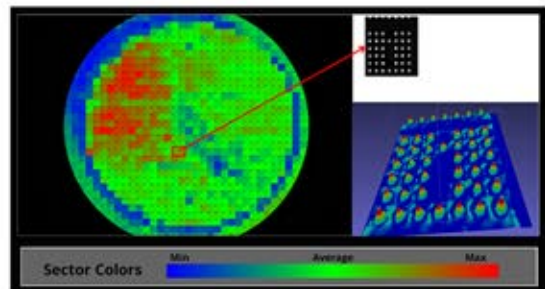- Detect & display defects like particles, scratches, missing patterns & bumps.

Highlights
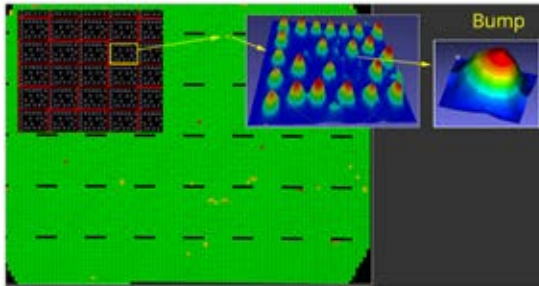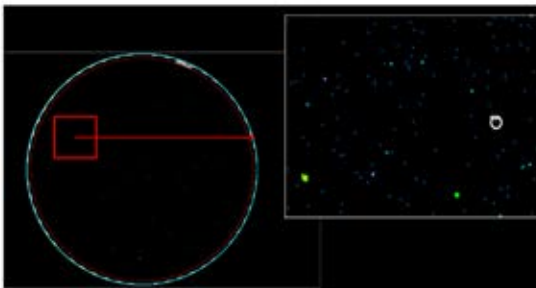

DETECTING THE DEFECTS

Bumps on the wafer:

- Identifying X,Y location(relative to notch), minimum height, maximum height, average height and diameter of the bump on a wafer.
- Information is saved in the industry standard KLARF format.

BINNING CAPABILITY :

- Missing bumps can be identified.
- High quality imaging providing a greater detail of intensities for detecting even floor variations & the height of bumps more accurately.

PARTICLES ON THE WAFER:

- Features capable of detecting the presence of particles, residues, damaged wafers, wafer edges, hard & soft defects with their locations, count and size with high binning accuracy.
- **32 Bit High Dynamic Range Process of Scanning:** Provides a wide range of intensity's for detecting sub micron particles(0.25 microns) to very large particles(many millimeters) with a single scan for front and back of the wafer.
- Automatic classification of defects though our computer algorithm process of deep learning(A.I.).

Application Features

Follows SEMI Standards for Job Handling	Recipe Management	User and Role Management	Access Control Based on Login	Defect/Particle Map in Standard Format	A.I. Available for Classifying Defects.	Signature Analysis
Charting Package for Professional Reporting	3D Viewer with Measurements	Die-to-Die Matching	2D and 3D Analysis	HDR Imaging	Edge Inspection	Automatic Notch Detection